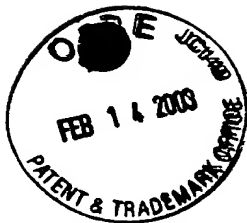


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#8/A
2/25/03
Mallish

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
SHOTARO UCHIDA : EXAMINER: IM, J.
SERIAL NO: 09/891,316 ✓ :
FILED: JUNE 27, 2001 ✓ : GROUP ART UNIT: 2811
FOR: SEMICONDUCTOR DEVICE
MANUFACTURING METHOD
AND SEMICONDUCTOR
DEVICE MANUFACTURED
THEREBY

RECEIVED
FEB 20 2003
TECHNOLOGY CENTER 2800

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Office Action of November 21, 2002, please amend the above-identified application as follows:

02/10/2003 SZEWDIE1 00000005 09891316

01 FEB 2003

84.00 DP

IN THE CLAIMS

✓
Please cancel Claims 1-7 without prejudice.

Please amend Claims 8, 11, 12, 15 and 20 to read as follows:¹ allowed

8. (Amended) A semiconductor device comprising:
a plurality of external leads;
a die pad adjacent to the plurality of external leads;

¹A marked-up copy of the amendments is attached hereto.

A1